TOSHIBA Photocoupler GaAs Ired & Photo-Transistor

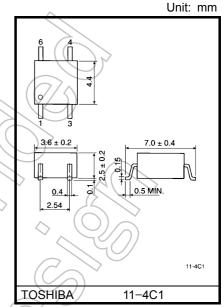
TLP124

Office Machine
Programmable Controllers
AC / DC-Input Module
Telecommunication

The TOSHIBA mini flat coupler TLP124 is a small outline coupler, suitable for surface mount assembly.

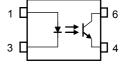
TLP124 consists of a photo transistor optically coupled to a gallium arsenide infrared emitting diode.

- Collector-emitter voltage: 80 V (min)
- Current transfer ratio: 100% (min)
 Rank BV: 200% (min)
- Isolation voltage: 3750Vrms (min)
- UL recognized: UL1577, file No. E67349



Weight: 0.09g (typ.)

Pin Configurations (top view)



- 1 : Anode
- 3 : Cathode
- 4 : Emitter
- 6 : Collector

Current Transfer Ratio

Classification	Curr			
	Ta =	25°C	Ta = -25~75°C	Marking of
	I _F = 1mA V _{CE} = 0.5V	I _F = 0.5mA V _{CE} = 1.5V	I _F = 1mA V _{CE} = 0.5V	Classification
Rank BV	200%	100%	100%	BV
Standard	100%	50%	50%	BV, Blank

(Note) Application type name for certification test, please use standard product type name, i. e. TLP124 (BV): TLP124

Absolute Maximum Ratings (Ta = 25°C)

	Characteristic	Symbol	Rating	Unit
	Forward current	lF	50	mA
	Forward current derating	ΔI _F / °C	–0.7 (Ta≥53°C)	mA / °C
LED	Peak forward current (100µs pulse, 100pps)	I _{FP}		A (
	Reverse voltage	V_{R}	5	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\
	Junction temperature	Tj	125	(°C)
	Collector-emitter voltage	V_{CEO}	80))
	Emitter-collector voltage	V _{ECO}	7	\(\sqrt{v}\)
	Collector current	Ic <	50	mA
Detector	Peak collector current (10ms pulse, 100pps)	ICP	100	mA
۵	Power dissipation	PC	150	mW
	Power dissipation derating (Ta ≥ 25°C)	ΔP _C / °C	1.5	mA / °C
	Junction temperature	4	125	°C
Stor	rage temperature range	T _{\$tg}	-55~125	°C
Оре	erating temperature range	Topr	(°C
Lea	d soldering temperature (10s)	T _{sol}	260	°C
Tota	al package power dissipation	Рт	200	mW
	al package power dissipation ating (Ta ≥ 25°C)	ΔP _T / °C	-2.0	mW / °C
	ation voltage , 1 minute, R.H. ≤ 60%) (Note 1)	BVS	3750	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

(Note 1) Device considered a two terminal device: Pins1, 3 shorted together and pins 4, 6 shorted together.

Recommended Operating Conditions

Characteristic	Symbol	Min	Тур.	Max	Unit
Supply voltage	V _{CC}	_	5	48	V
Forward current	lF	_	1.6	20	mA
Collector current	IC	_	1	10	mA
Operating temperature	T _{opr}	-25	_	75	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

Individual Electrical Characteristics (Ta = 25°C)

	Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
	Forward voltage	V _F	I _F = 10 mA	1.0	1.15	1.3	V
LED	Reverse Current	I_{R}	V _R = 5 V	-((10	μΑ
	Capacitance	C _T	V = 0, f = 1 MHz	4	30	_	pF
	Collector-emitter breakdown voltage	V _(BR) CEO	I _C = 0.5 mA	80			V
o.	Emitter–collector breakdown voltage	V _{(BR) ECO}	I _E = 0.1 mA	7)	_		V
Detector	Collector dark current	Della standarda sussant	V _{CE} = 48 V)	10	100	nA
Collector dark current	ID	V _{CE} = 48 V, Ta = 85°C) —	2	50	μΑ	
	Capacitance collector to emitter	C _{CE}	V = 0, f = 1 MHz	_	12	_	pF

Coupled Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition		MIn	Тур.	Max	Unit
Current transfer ratio	I _C /I _E	I _F = 1mA, V _{CE} = 0.5 V		100	_	1200	%
Current transfer fatto)) ''C' 'F		Rank BV	200	_	1200	/0
Low input CTP	1- /1- 11	$I_F = 0.5 \text{ mA}, V_{CE} = 1.5 \text{ V}$		50	_	-	%
Low input CTR	I _C / I _F (low)		Rank BV	100	_	-	70
		$I_C = 0.5 \text{ mA}, I_F = 1 \text{ mA}$		_	_	0.4	
Collector-emitter saturation voltage	V _{CE (sat)}	I _C = 1 mA, I _F = 1 mA		_	0.2	-	V
2/\\)	\wedge	>	Rank BV	_	_	0.4	
Off-state collector current	(C(off)	V _F = 0.7V, V _{CE} = 48 V		_	_	10	μΑ

Coupled Electrical Characteristics (Ta = -25~75°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Current transfer ratio	I _C / I _F	I _F = 1mA, V _{CE} = 0.5 V	50	_	_	%
Current transfer fatto		Rank BV	100	_	_	%
Low input CTR	la / l= a	I _F = 0.5 mA, V _{CE} = 1.5 V	_	50	_	%
Low input CTR	I _C / I _{F (low)}	Rank BV	_	100	-	%

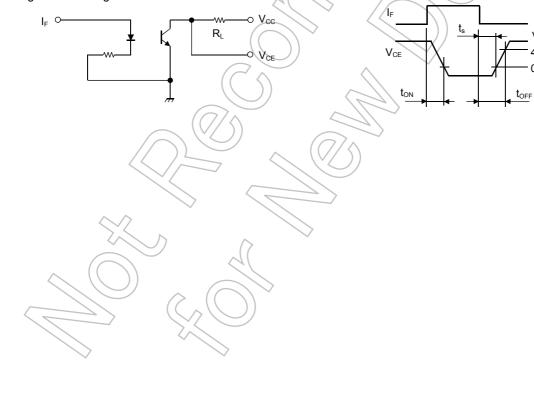
Isolation Characteristics (Ta = 25°C)

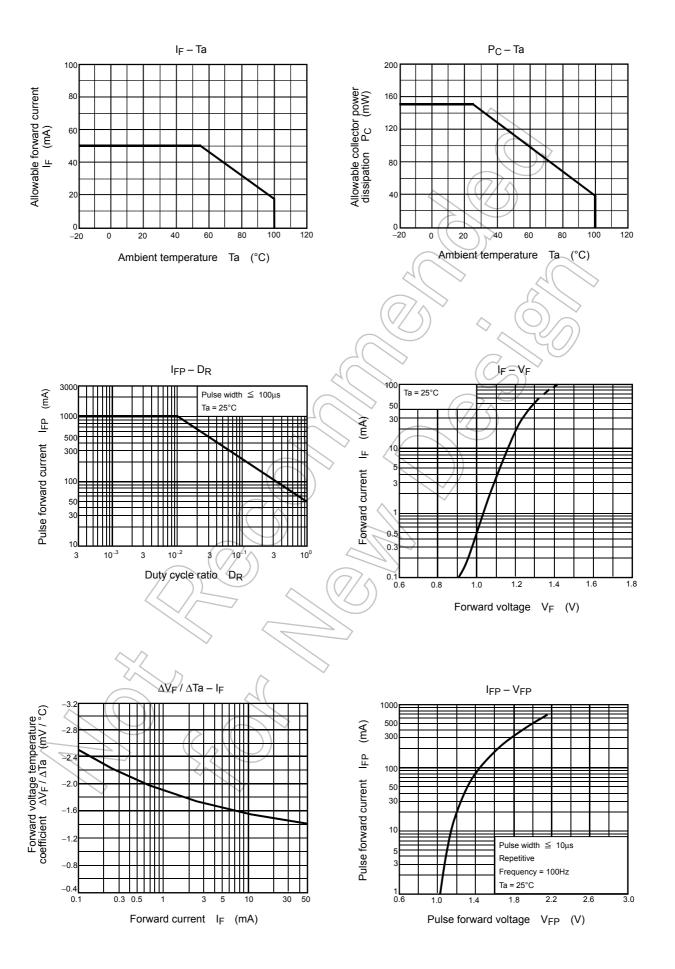
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Capacitance (input to output)	CS	V _S = 0, f = 1 MHz	_	0.8	_	pF
Isolation resistance	R _S	V _S = 500 V, R.H. ≤ 60%	5×10 ¹⁰	10 ¹⁴	_	Ω
Isolation voltage		AC, 1 minute	3750	_	_	V
	BV_S	AC, 1 second, in oil	((-)	10000	_	V _{rms}
		DC, 1 minute, in oil		10000	_	V _{dc}

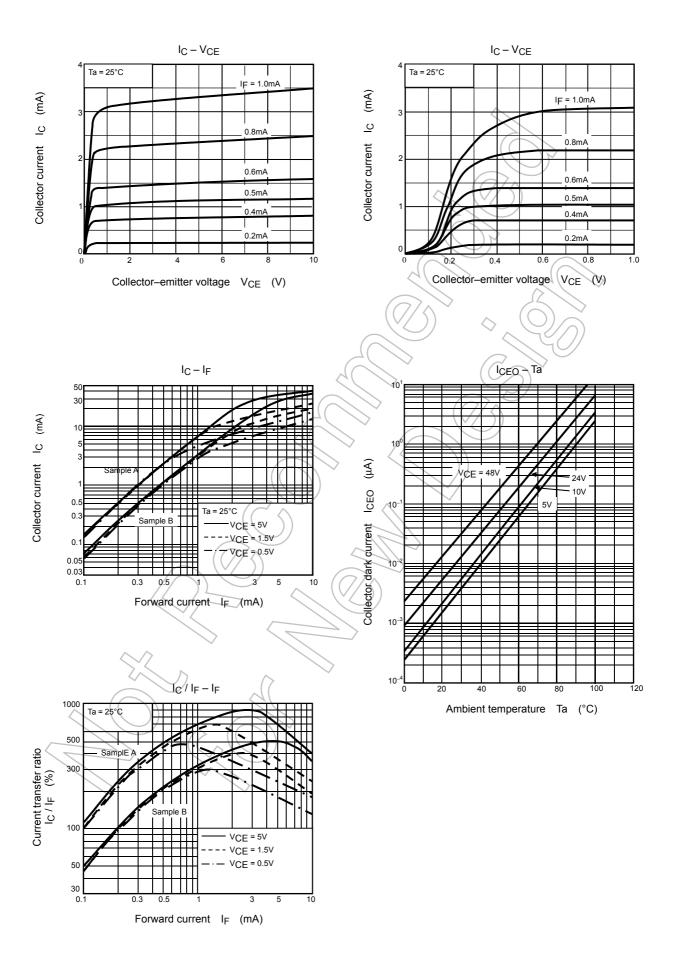
Switching Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Rise time	t _r	40	_	8	7	
Fall time	t _f	$V_{CC} = 10 \text{ V, I}_{C} = 2 \text{ mA}$ $R_{L} = 100\Omega$	-	8	- 1	116
Turn-on time	t _{ON}	$R_L = 100\Omega$	-(()10_		μs
Turn-off time	toff	· ·	4	(8)	/ —	
Turn-on time	t _{ON}		7 -	> 10	-	
Storage time	ts	$R_L = 4.7 \text{ k}\Omega$ (Fig.1) $V_{CC} = 5 \text{ V}, I_F = 1.6 \text{ mA}$	/)	50	_	μs
Turn-off time	toff			300	_	

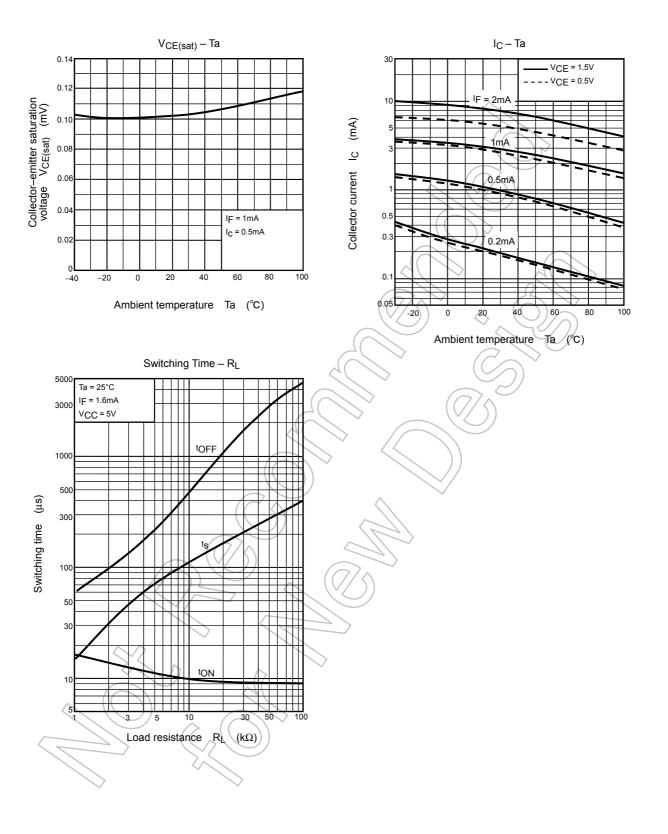
Fig. 1 Switching time test circuit







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